

Ceramic Plate Series Thermoelectric Cooler

The CP14-127-10-L1-EP-W12 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 32.2 Watts when $\Delta T=0$ and a maximum ΔT of 70.5 °C at Qc = 0.

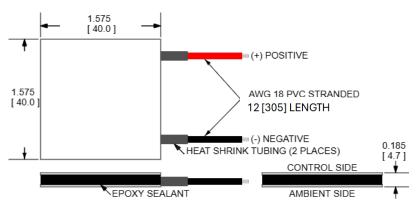
Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Peltier Cooling for Machine Vision





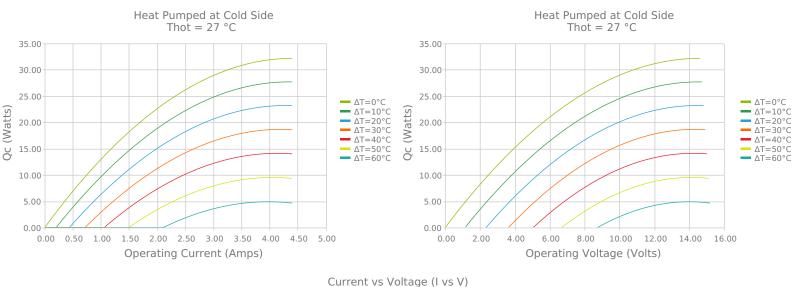
CERAMIC MATERIAL: Al₂O₃
SOLDER CONSTRUCTION: 138°C. BiSn

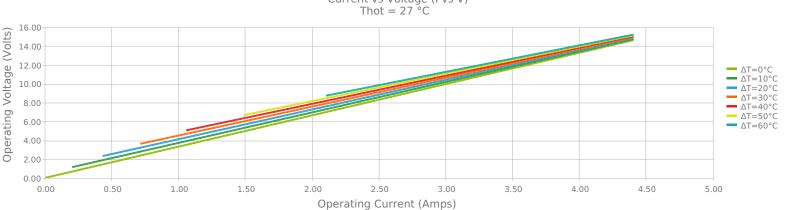
INCHES [MM]

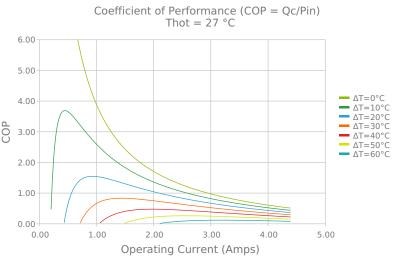
Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

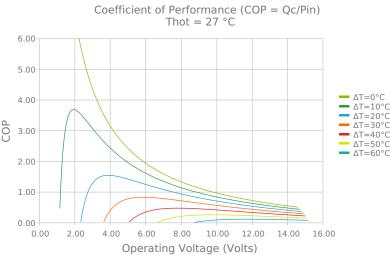
ELECTRICAL AND THERMAL PERFORMANCE

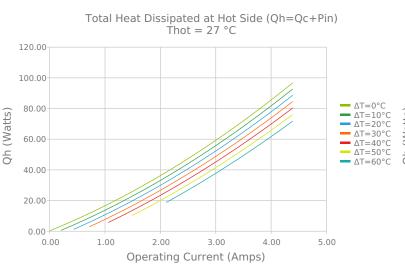
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the AMBIENT side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

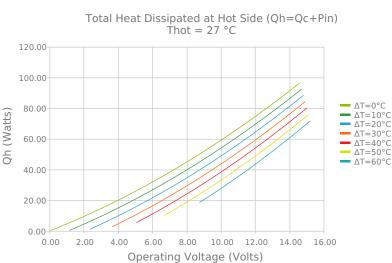


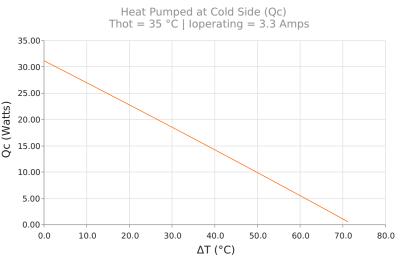


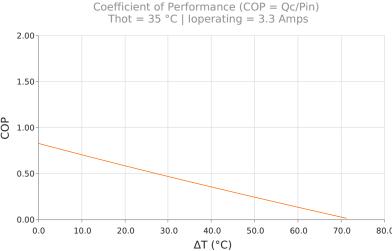














SPECIFICATIONS

Hot Side Temperature

 $Qcmax (\Delta T = 0)$

 $\Delta T max (Qc = 0)$

Imax (I @ \Delta Tmax)

Vmax (V @ Δ Tmax)

Module Resistance

Max Operating Temperature

Weight

27.0 °C	35.0 °C	50.0 °C	
32.2 Watts	33.2 Watts	34.9 Watts	
70.5°C	73.5°C	78.8°C	
3.9 Amps	3.9 Amps	3.8 Amps	
13.9 Volts	14.4 Volts	15.4 Volts	
3.32 Ohms	3.46 Ohms	3.72 Ohms	
80 °C			
24.0 gram(s)			

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L1	$4.700 \pm 0.025 \text{ mm}$ $0.185 \pm 0.0010 \text{ in}$	0.025 mm / 0.025 mm 0.001 in / 0.001 in	Lapped	Lapped	305 mm 12 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Ероху	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

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